

TECHNICAL SPECIFICATION

**Process management for avionics – Electronic components for aerospace,
defence and high performance (ADHP) applications –
Part 1: General requirements for high reliability integrated circuits and discrete
semiconductors**



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CONTENTS

FOREWORD.....	6
INTRODUCTION.....	8
1 Scope.....	9
2 Normative references	9
3 Terms, definitions and abbreviated terms	10
3.1 Terms and definitions.....	10
3.2 Abbreviated terms.....	12
4 Technical requirements	14
4.1 General.....	14
4.1.1 Overview	14
4.1.2 Automotive components.....	15
4.2 Procedures	15
4.2.1 General	15
4.2.2 Product discontinuance	15
4.2.3 ESD protection during manufacture	15
4.2.4 Specification control	16
4.2.5 Traceability including anti-counterfeit measures	16
4.3 Product or process change notification (PCN).....	16
4.3.1 General	16
4.3.2 Notification	16
4.3.3 Notification details	16
4.3.4 Notifiable changes	17
4.4 Shipment controls	17
4.4.1 General	17
4.4.2 Shipping container and date code marking	17
4.4.3 Date code remarking	17
4.4.4 Inner container formation.....	17
4.4.5 Date code age on delivery	18
4.4.6 ESD marking	18
4.4.7 MSL.....	18
4.4.8 Lead-free marking	18
4.4.9 Labels	18
4.5 Electrical.....	19
4.5.1 General	19
4.5.2 Electrical test.....	19
4.5.3 Electrical parameter assessment	19
4.5.4 SDRAM memories	20
4.5.5 Logic families	20
4.5.6 Power MOSFETs	20
4.5.7 Silicon rectifier diodes	20
4.6 Mechanical	20
4.6.1 General	20
4.6.2 Device marking.....	20
4.6.3 Small packages	20
4.6.4 Moisture sensitivity	20
4.6.5 Robustness of hermetic seals	21

4.6.6	Termination finishes	21
4.7	Audit capability	21
4.7.1	General	21
4.7.2	Internal quality audits	21
4.7.3	Subcontract manufacturing	22
4.8	Quality assurance	22
4.8.1	General	22
4.8.2	Quality system	22
4.8.3	Sampling plans	22
4.8.4	Failure analysis support	22
4.8.5	Outgoing quality	22
4.9	Qualification	23
4.9.1	General	23
4.9.2	Methodology	24
4.9.3	Test samples	25
4.9.4	Qualification categories	26
4.9.5	Maintenance of qualification standard	26
4.9.6	In-process test results	26
4.9.7	Product monitor results	30
4.9.8	References	30
4.9.9	Qualification report	30
4.9.10	Archiving	30
4.9.11	Qualification by similarity	30
4.9.12	Similarity assessment	30
4.10	Reliability	31
4.10.1	General	31
4.10.2	Operating reliability	31
4.10.3	Failure criteria	31
4.10.4	Corrective action	32
4.10.5	Warranty	32
4.10.6	Single event effects (SEEs)	32
4.11	Product monitor	32
4.11.1	General	32
4.11.2	Monitor programme	32
4.11.3	Problem notification	32
4.11.4	Data reporting	33
4.11.5	Samples	33
4.11.6	Corrective action	33
4.11.7	Product monitor results	33
4.11.8	Accumulated test data	33
4.12	Environmental health and safety (EHS)	34
4.12.1	General	34
4.12.2	EHS compliance	34
4.12.3	Device handling	34
4.12.4	Device materials	34
4.13	Shipping containers	34
4.13.1	General	34
4.13.2	ESD requirements	34
4.13.3	Magazine reuse	36

4.13.4	Tubes	36
4.13.5	Trays	36
4.13.6	Tape and reel	37
4.14	Compliance with internal standards.....	37
Annex A	(informative) Test code (TC) information	38
A.1	General.....	38
A.2	TC1 – Autoclave (ATC)	38
A.3	TC2 – Bond strength, internal (BS)	38
A.4	TC3 – Die shear strength (DS).....	38
A.5	TC4 – Electromigration (EM).....	38
A.6	TC5 – Electrostatic discharge (ESD).....	39
A.7	TC6 – Electrical test (ET).....	39
A.8	TC7 – Electrical distributions (EDs).....	39
A.9	TC8 – Flammability (FL).....	40
A.10	TC9 – Hot carrier injection (HCI).....	40
A.11	TC10 – Hermeticity (HE)	40
A.12	TC11 – High temperature bake (HTB)	40
A.13	TC12 – High temperature blocking bias (HTBB)	41
A.14	TC13 – High temperature gate bias (HTGB).....	41
A.15	TC14 – High temperature reverse bias (HTRB)	41
A.16	TC15 – High temperature operating life (HTOL)	41
A.16.1	General	41
A.16.2	Qualification conditions.....	41
A.16.3	Test results assessment	42
A.16.4	Temperature acceleration factor	42
A.16.5	Supply voltage acceleration factor	43
A.17	TC16 – Latch-up (LU)	43
A.18	TC17 – Lead integrity (LI)	43
A.19	TC18 – Lid torque (LT).....	43
A.20	TC19 – Mechanical sequence (MS).....	43
A.20.1	General	43
A.20.2	Constant acceleration	44
A.20.3	Vibration (variable frequency).....	44
A.20.4	Mechanical shock	44
A.21	TC20 – Marking permanency (MP).....	44
A.22	TC21 – Non-volatile memory operating life (NVL).....	44
A.23	TC22 – Time dependent dielectric breakdown (oxide integrity) (OI).....	45
A.24	TC23 – Package dimensions (PD).....	45
A.25	TC24 – Power cycling (PTC).....	45
A.26	TC25 – Resistance to solder heat (RSH).....	45
A.27	TC26 – Solder preconditioning (PC).....	46
A.28	TC27 – Solderability (SD)	46
A.29	TC28 – Soft error rate (SER).....	46
A.30	TC29 – Steady state operating life (SSOL).....	47
A.31	TC30 – Temperature cycling (TPC).....	47
A.32	TC31 – Temperature humidity reverse bias (THRB)	48
A.33	TC32 – Temperature humidity bias (THB or HAST)	48
A.34	TC33 – Terminal strength (TS).....	48
A.35	TC34 – Thermal resistance (thermal impedance) (TR)	48

A.36	TC35 – Visual inspection (VI).....	49
A.36.1	TC35a – External visual inspection	49
A.36.2	TC35b – Internal visual inspection	49
A.37	TC36 – Water vapour content, internal (WV)	50
A.38	TC37 – X-ray inspection (XR)	50
A.39	TC38 – Moisture sensitivity level (MSL)	50
A.40	TC39 – Ball shear test (BST)	50
A.41	TC40 – Negative bias temperature instability (NBTI)	50
A.42	TC41 – Accelerated tin whisker test	51
Annex B (informative)	Typical automotive component requirements	52
Annex C (informative)	Requirement matrix for IEC TS 62686-1 verification	54
Bibliography	78
Table 1	– Label requirements.....	19
Table 2	– Internal quality audit requirements.....	21
Table 3	– Outgoing quality	23
Table 4	– Technology/family qualification and device qualification (1 of 3)	27
Table 5	– Product monitor tests	34
Table A.1	– Conditions of the DC over voltage stress method of JP001.01 or IEC 62416 test.....	40
Table A.2	– Examples of temperature acceleration factors	42
Table A.3	– Dip and look test references.....	46
Table A.4	– Parameter values for consideration	47
Table A.5	– Test conditions.....	47
Table A.6	– Test methods	48
Table C.1	– Requirement matrix.....	54

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PROCESS MANAGEMENT FOR AVIONICS – ELECTRONIC COMPONENTS FOR AEROSPACE, DEFENCE AND HIGH PERFORMANCE (ADHP) APPLICATIONS –

Part 1: General requirements for high reliability integrated circuits and discrete semiconductors

FOREWORD

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- the required support cannot be obtained for the publication of an International Standard, despite repeated efforts, or
- the subject is still under technical development or where, for any other reason, there is the future but no immediate possibility of an agreement on an International Standard.

Technical Specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC TS 62686-1, which is a Technical Specification, has been prepared by IEC technical committee 107: Process management for avionics.

This third edition cancels and replaces the second edition, published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) update related to obsolescence of STACK Specification S/0001 revision 14 notice 3;
- b) addition of alternative automotive methods of compliance and revision of Annex B initially related to cross-reference to STACK Specification S/0001;
- c) addition of an Annex C to include a requirement matrix for IEC TS 62686-1 verification.

The text of this Technical Specification is based on the following documents:

Draft TS	Report on voting
107/349/DTS	107/361A/RVDTS 107/361/RVDTS

Full information on the voting for the approval of this Technical Specification can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62686 series, published under the general title *Process management for avionics – Electronic components for aerospace, defence and high performance (ADHP) applications*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This part of IEC 62686 includes all the requirements of the now obsolete STACK Specification S/0001 revision 14 notice 3 and also contains revisions for alternative strategies using for example automotive standards together with the option of using various qualification test methods and additional test information.

This document complements IEC TS 62564-1 which is used for ADHP applications when additional manufacturers' data is required beyond the publicly available original component manufacturers' published data sheets (for example when additional thermal performance data is required for thermally challenging applications or when additional verification data is needed, for example to comply with the requirements of RTCA DO-254/EUROCAE ED-80 for complex components for flight critical applications, etc.).

This document can also be used to comply with the typical qualification requirements of IEC TS 62564-1. Further guidance is given in IEC 62239-1.

NOTE Existing STACK certified manufacturers can be audited by IECQ under the new STACK-IECQ joint venture or alternatively to the new IECQ automotive scheme.

PROCESS MANAGEMENT FOR AVIONICS – ELECTRONIC COMPONENTS FOR AEROSPACE, DEFENCE AND HIGH PERFORMANCE (ADHP) APPLICATIONS –

Part 1: General requirements for high reliability integrated circuits and discrete semiconductors

1 Scope

This part of IEC 62686, which is a Technical Specification, defines the minimum requirements for general purpose "off the shelf" COTS (commercial off-the-shelf) integrated circuits and discrete semiconductors for ADHP (aerospace, defence and high performance) applications.

This document applies to all components that can be operated in ADHP applications within the manufacturers' publicly available data sheet limits in conjunction with IEC 62239-1. It can be used by other high performance and high reliability industries, at their discretion.

ADHP application requirements are not necessarily fulfilled by this document alone. ADHP OEMs (original equipment manufacturers) might need to consider redesigning their products or conducting further testing to verify suitability in ADHP applications using their IEC 62239-1 ECMP procedures. Alternatively, a component in accordance with IEC TS 62564-1 can be more suitable.

NOTE Component qualification and outgoing quality discussed herein do not address component atmospheric radations SEE effects per IEC 62396-1.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ANSI/EIA-556, *Outer Shipping Container Bar Code Label Standard*

ANSI/ESD S541, *Packaging Materials Standards for ESD Sensitive Items*

IPC/JEDEC J-STD-609, *Marking and Labeling of Components, PCBs and PCBAs to Identify Lead (Pb), Lead-Free (Pb-Free) and Other Attributes*

JEDEC/IPC/ECIA J-STD-048, *Notification Standard for Product Discontinuance*

JEP130, *Guidelines for Packing and Labeling of Integrated Circuits in Unit Container Packing*

JESD471, *Symbol and Label for Electrostatic Sensitive Devices*

J-STD-046, *Customer Notification of Product/Process Changes by Solid-State Suppliers*